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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Jung-Huei Peng	07/08/2013
Chia-Hua Chu	07/08/2013
Yao-Te Huang	07/08/2013
Chin-Yi Cho	07/08/2013
Li-Min Hung	07/08/2013
Chun-Wen Cheng	07/08/2013

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13973812

OP $40.00 13973812

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	24061.2506

NAME OF SUBMITTER:	Linda Ingram
Signature:	/Linda Ingram/
Date:	08/22/2013
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Docket No.: 2013-0052/24061.2506
Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

(1) Jung-Huei Peng of 7F-1, No. 6, Zihciang 6th Street
Jhubei City, Hsinchu Hsien, Taiwan, R.O.C.

(2) Chia-Hua Chu of No. 1, Lane 176, Aikou 6th Street
Zhubei City, Hsinchu County 302
Taiwan, R.O.C.

(3) Yao-Te Huang of 10F-3, No. 419-3, Section 2
Gongdao 5th Road, East District
Hsinchu City 300, Taiwan, R.O.C.

(4) Chin-Yi Cho of 392-3, Cisian 1st Road
Sinsing District
Kaohsiung City, Taiwan, R.O.C.

(5) Li-Min Hung of 14F-5, No. 28, Bainian 3rd Street
Longtan Township
Taoyuan County 325, Taiwan, R.O.C.

(6) Chun-Wen Cheng of No. 15, Alley 11, Lane 100, Jiafeng 1st Street
Zhubei City, Hsinchu County 302
Taiwan, R.O.C.

have invented certain improvements in

STRUCTURE AND METHOD FOR INTEGRATED MICROPHONE

for which we have executed an application for Letters Patent of the United States of America,

_______ of even date filed herewith; and
__X__ filed on August 22, 2013, and assigned application number 13/973,812; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Jung-Huei Peng

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Dated: ✓ 7/8/2013 Jung-Huei Peng

✓ Jung-Huei Peng
Inventor Signature

Inventor Name: Chia-Hua Chu

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Dated: ✓ 2013.7.8

✓ Chia-Hua Chu
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Dated: ✓ 2013.7.8 Yao-Te Huang

✓ Yao-Te Huang
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Docket No.: 2013-0052/24061.2506
Customer No.: 000042717

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Dated: ✓ 7/8/2013

✓ Chin-Yi Cho
Inventor Signature

Inventor Name: Li-Min Hung

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Dated: ✓ 7/8/2013

✓ LI-MIN HUNG
Inventor Signature

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Dated: ✓ 07/08/2013

✓ Chun-Wen Cheng
Inventor Signature
